

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A semiconductor device comprising:
 - ~~an inner lead having a sloping section sloping upward and outward;~~
 - a die pad;
 - a semiconductor chip having an electrode and bonded to the die pad;
 - an inner lead having a sloping section sloping upward and outward,
 - when a surface of the die pad which the semiconductor chip is bonded faces
 - upward;
 - a wire electrically connecting the inner lead to the electrode;
 - a sealing section sealing the inner lead, the semiconductor chip, and the wire; and
 - an outer lead extending outward from the sealing section;
 - wherein the wire is bonded to the sloping section of the inner lead.
- 2-4. (Cancelled).
5. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a second sloping section sloping downward and outward from a higher end of the sloping section.
6. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a portion extending in a horizontal direction and connected to the outer lead.

7. (Previously Presented): The semiconductor device as defined in claim 1, wherein a bonding position between the wire and the inner lead is lower than the position of the electrode.

8. (Cancelled).

9. (Original): The semiconductor device as defined in claim 1, wherein a surface of the die pad opposite to the semiconductor chip is exposed from the sealing section.

10. (Original): A circuit board on which the semiconductor device as defined in claim 1 is mounted.

11. (Original): An electronic instrument comprising the semiconductor device as defined in claim 1.

12-20. (Cancelled).

21. (Currently Amended): A semiconductor device comprising:

an inner lead having a first sloping section sloping upward and outward, the inner lead having a second sloping section sloping downward and outward from a higher end of the first sloping section, when a surface of the die pad which the semiconductor chip is bonded faces upward;

a die pad;

a semiconductor chip having an electrode and bonded to the die pad;

a wire electrically connecting the inner lead to the electrode;

a sealing section sealing the inner lead, the semiconductor chip, and the wire; and

an outer lead extending outward from the sealing section.